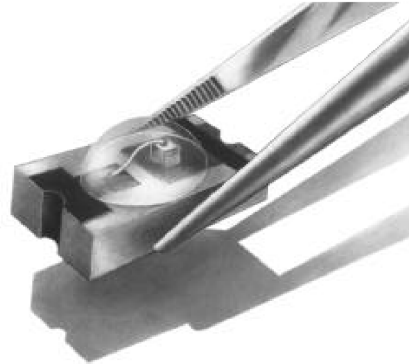


## CR 12 R

### Features

- Solid State Ceramic Chip
- Surface Mounting Device
- High Power Thermal Absorption
- Superior Light Uniformity Over 180°
- End to End Side to Side Stackable Down to a Pitch of 1,33mm
- Solder Pads Conform to Mil-Std 883B
- Red Diffused Lens

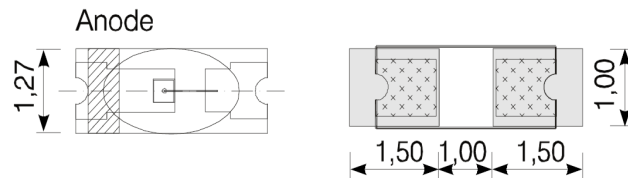
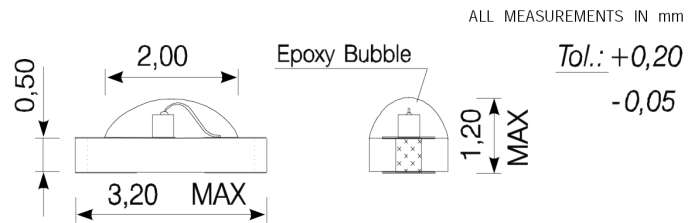


### Applications

- Ideal For Back Light Applications
- Custom Configurations

### Maximum Ratings (Ta=25°C)

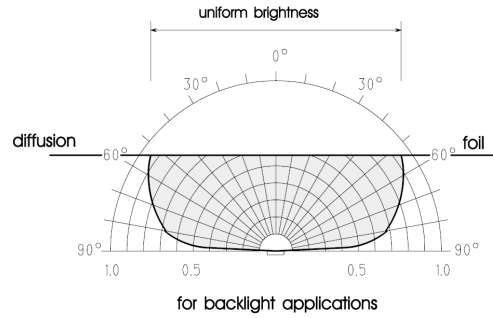
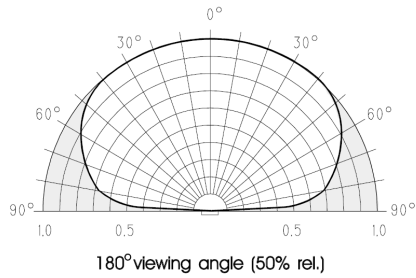
Characteristic	Symbol	Max.	Unit
Forward Current	I <sub>F</sub>	75	mA
Reverse Voltage	V <sub>R</sub>	100	V
Power Dissipation	P <sub>D</sub>	130.00	mW
Operating Temperature	T <sub>opr</sub>	-25 ~ +80	°C
Storage Temperature	T <sub>stg</sub>	-25 ~ +120	°C
Soldering Temperature	T <sub>sol</sub>	250	°C
Soldering Time	-	for 10 sec. max	-



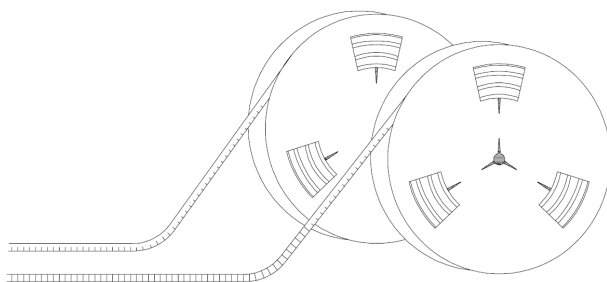
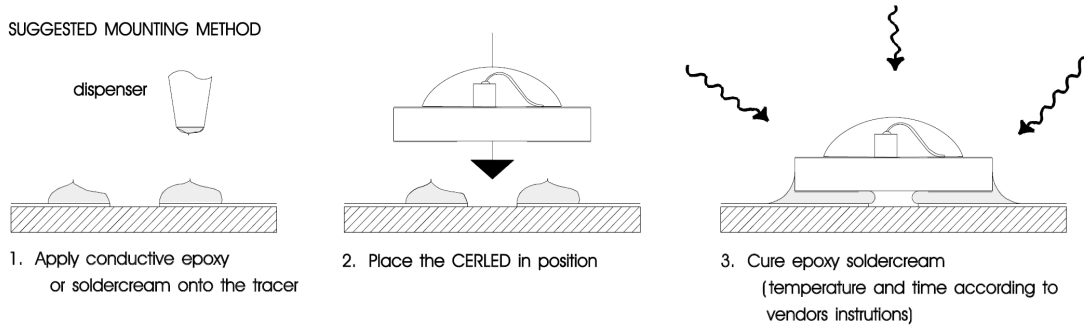
### Opto-Electrical Characteristics (Ta=25°C)

Characteristic	Symbol	Test Condition	Min	Typ	Max	Unit
Forward Voltage	V <sub>F</sub>	I <sub>F</sub> =20mA	-	2.10	2.40	V
Reverse Current	I <sub>R</sub>	V <sub>R</sub> =5V	-	-	100	μA
Luminous Intensity	I <sub>v</sub>	I <sub>F</sub> =20mA	3.20	7.20	-	mcd
Viewing Angle	2θ <sup>1/2</sup>	-	-	180°	-	deg.
Peak Wavelength	λ <sub>p</sub>	I <sub>F</sub> =20mA	-	630	-	nm
Dominant Wavelength	λ <sub>d</sub>	I <sub>F</sub> =20mA	-	624	-	nm
Spectral Line Half Width	Δλ	I <sub>F</sub> =20mA	-	23	-	nm

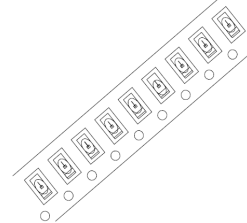
**CR 12 R Graphs**



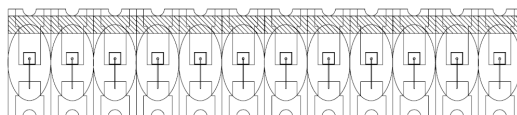
**SUGGESTED MOUNTING METHOD**



Special Packing:  
standard 8 mm blister tape



**ARRAYS**



code to order strips:  
CR 10 XX -\_\_ 10  
No of LEDs

Available in strips up to 12 CERLEDs with a max. pitch tolerance in spacing and linearity of  $\pm 0,01$  mm between chip centers.